

IEEE 中華民國分會補助各支會活動成果報告表

96.5.3

會議名稱： 2009 年亞洲固態電路研討會(A-SSCC 2009)		
舉辦日期：98/11/16-18		
主辦機構：IEEE SSCS Taipei Chapter		舉辦地點：台北圓山飯店
舉辦支會：SSC37	支會主席：陳巍仁	TEL：03-5712121*54172
原預估出席人數：300 人 會議當天實際出席人數：340 人		

會議重要成果：（請確實填寫，作為下屆補助經費參考）

由於近年來全球半導體工業以驚人的速度成長，其中亞太地區又深具經濟發展潛力，亞洲固態電路會議的舉行，不僅為國內相關產業之研究與發展提供一個最佳的交流機會與場所，更可以透過技術與意見的廣泛交流，將有助於提昇我國在尖端科技領域中的國際地位。

具體成果：

- 1) 促成國際間電子資訊相關從業人員及研究人員之合作。
- 2) 讓與會的外賓對半導體工業的發展有更加深入的探討。
- 3) 給予國內相關產業之研究與發展提供一個最佳的交流平台。
- 4) 促進國際間學術界及工業界此方面之交流，增進國內競爭力。

Asian Solid-State Circuits Conference (A-SSCC) is an international forum for advances in solid-state circuits design held in Asia. In the very fifth year under its name, the A-SSCC'09 held in Taiwan, received more than 280 papers and had up to 340 attendees focusing on the Asia region. Other than the conference programs such as paper, plenary and tutorial sessions, A-SSCC features a practical industry program and student design contest. Practical industry program presented on cutting-edge IC products which promoted the communication and collaboration between industry and academia. Student design contest awarding the best student design selected from the 10 accepted student papers encouraged excellence in chip designs by providing competition between students at universities and colleges. For over all, A-SSCC'09 is of great benefit to domestic industry and academia and the status of our country has raised in international circuits design society.



需繳交資料：

1. 活動文章（約500字，MS-Word格式，中英文版各乙篇）
2. 照片2-4張（JPEG檔/300dpi）

※ 上述資料請自行登錄於分會網頁，並將電子檔e-mail至陳虹妙

(nao@cc.nctu.edu.tw)信箱。



Call for Participation



2009 IEEE Asian Solid-State Circuits Conference (A-SSCC)

Nov. 16 - Nov. 18, 2009

The Grand Hotel, Taipei, Taiwan

Green Circuits for a Sustainable Society



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Sponsored by
IEEE Solid-State Circuits Society
Organized by
IEEE region 10 SSCS chapters
Official Website
<http://www.a-sscc.org>

The IEEE SSCS (Solid-State Circuits Society) fully supported Asian Solid-State Circuits Conference (SSCC) 2009 is an international forum for advances in solid-state circuits design held in Asia. Other than conventional conference programs such as paper and plenary sessions, A-SSCC features a practical industry program. In the very fifth year under its name, the A-SSCC'09 received more than 280 papers. Technical program committee members are a balance of the industry and the academia and as a result, the technical program should interest both industry and academia.

Technical Paper Focus

"A DVS Embedded Power Management for High Efficiency Integrated SoC in UWB System"

"A 9b 100MS/S 1.46mW SAR ADC in 65nm CMOS"

"A Micro-Network on Chip with 10-Gb/s Transmission Link"

"Tera-Scale Performance Image Stream Processor with SoC Architecture for Multimedia Content Analysis"

"A 110GHz Inductor-Less CMOS Frequency Divider"

"A 1.35GHz All-Digital Fractional-N PLL with Adaptive Loop Gain Controller and Fractional Divider"

"A 1.3 pJ/B Inductive Coupling Transceiver with Adaptive Gain Control for Cm-Range 50Mbps Data Communication"

"A Low Supply Voltage Operation SRAM with HCI trimmed Sense Amplifiers"

"A 45nm 8-Core Enterprise Xeon® Processor"

Plenary Talks

• **Dr. Ho-Ming Tong** (Chief R&D Officer & GM, ASE Group, Taiwan)

"Green Future: IC Packaging Opportunities Abound"

• **Dr. Hisatsune Watanabe** (President, Semiconductor Leading Edge Technologies Inc., Japan)

"Nanoelectronics Devices: More CMOS, Fusion CMOS and Beyond CMOS"

• **Dr. Eric Vittoz** (Professor, Swiss Federal Institute of Technology, Lausanne, Switzerland)

"Weak Inversion for Ultra Low-Power and Very Low-Voltage Circuits"

Evening Panels

"Toward Low Voltage (0.5V) Design: Will Challenges Limit Operation?"

Moderator: Sreedhar Natarajan, (TSMC)

Panelists: K. Arimoto (Renesas), A. Burnet (Toumaz Medical), B. Nikolic (UCB), A. Keshavarzi(TSMC), P. Rickert (TI), and more

"Gigabit Transceiver: a Panacea or a Poison?"

Moderator: Mehmet Soyuer (IBM)

Panelists: M. Fujishma (Hiroshima Univ.), K. Nishikawa (NTT), B.Shung (SiBeam), L. Loh (MediaTek Inc.), A. Poon(Stanford Univ.), and more

Special Lecture

"All you need to know to write a winning ISSCC paper and give a smashingly good presentation" **Dr. Jan Van Der Spiegel** (Professor, University of Pennsylvania, USA)

Industrial Program

In the industry program, papers on cutting-edge IC products are presented with application, design and measurement information. There are two parallel sessions with 7 papers from Intel (USA), Toshiba (Japan), Samsung (USA), Microsystems (USA), Rambus (USA), Innovision R&T (UK), Future Communication IC (Korea) and MediaTek Inc., (Taiwan).

Student Design Contest

10 outstanding chip designs from the accepted student papers will make real demonstrations on the conference stage with authors' explanation. The best student design will be selected among those 10 demonstrations reflecting high research standards of Asian academies.

Important Dates:

Deadline of Early Registration:

Sept. 30, 2009 23:59

Taiwan(GMT+8)

Regular Registration:

Oct. 1, 2009 and onward

Tutorials

"Silicon Microelectronic Chips in the Human Healthcare and Life Sciences" Donhee Ham (Harvard Univ.)

"Inductive-Coupling Through-Chip Interface for 3D System Integration" Tadahiro Kuroda (Keio Univ.)

"Emerging ADC design" Un-Ku Moon (Oregon State Univ.)

"Advanced RF and Analog Design in the Nano-Meter Era" Bram Nauta (Univ. of Twente)